

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 10/789,914  
Filing Date: February 27, 2004  
Applicant: Hosomi et al.  
Title: Resin Composition, Prepeg, Laminate and Semiconductor Package  
Attorney Docket: 2497-000002/CP

**CERTIFICATE OF EFS SUBMISSION (37 CFR §1.8(a)(1)(1)(C))**

I hereby certify that on January 10, 2008, the following correspondence:

Name of Paper:

1. Petition To Claim Benefit Under 35 USC 365(C) and 119(b) - (2 pages)
2. Supplemental Application Data Sheet -- (3 pages)
3. Fee Transmittal -- (1 page)

Fees:

1. Petition Fee set forth in §1.17(t) in the amount of: \$1410.00 payable by Deposit Account No. 08-0750

is being submitted to the Patent and Trademark Office via the Office Electronic Filing System in accordance with §1.6(a)(4).

Dated: January 10, 2008

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